

<<现代应用集成电路设计>>

图书基本信息

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内容概要

本书基于作者周电在美国大学十几年教授“现代应用集成电路设计”课程的手稿整理而成，主要内容包括应用集成电路设计流程、设计指标定义和规范、逻辑电路设计、物理设计、时间功耗性能分析及验证测试。

读者需要有数字集成电路和硬件描述语言（VHDL）的基础知识。

按照具体课程设置的要求，本书可用于一个学期的教学内容，包括应用集成电路设计流程、设计指标定义和规范、逻辑电路设计及物理设计。

关于集成电路发展的前沿问题，本书在第7章和第8章中以研究课题为背影介绍了基础知识。

本书可作为电子和计算机工作专业的大学四年级或硕士研究生教材，也适于集成电路设计的专业人员参考阅读。

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